

## Sputter tool – Denton Explorer 14

- Depositing **Cr, Al, Ag, NiO, ZnO, AZO** layers
- Sample Sizes: Pieces – 6" wafer
- Target Size: 3 inch
- Base Pressure  $\sim 2.2 \times 10^{-6}$  Torr
- Pump Time  $\sim 3$  Hours
- Operation Gas Flow  $\sim$  Ar, 30sccm
- RF or DC

